



**ALPHA & OMEGA**  
SEMICONDUCTOR

**AOCA32106E**

**12V Common-Drain Dual N-Channel MOSFET**

### General Description

- Trench Power MOSFET Technology
- Low  $R_{SS(ON)}$
- With ESD protection to improve battery performance and safety
- Common drain configuration for design simplicity
- RoHS and Halogen-Free Compliant

### Applications

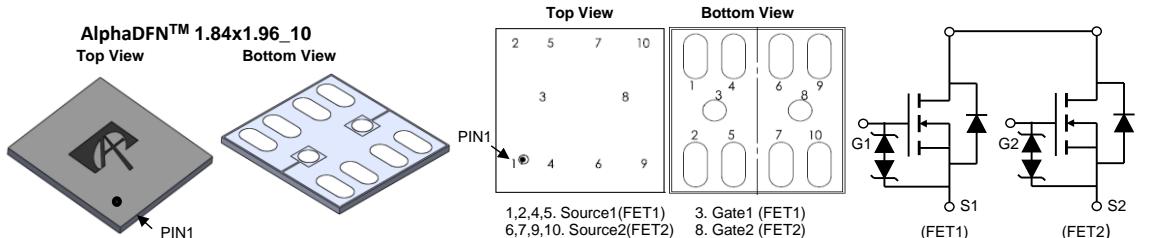
- Battery protection switch
- Mobile device battery charging and discharging

### Product Summary

$V_{SS}$	12V
$R_{SS(ON)}$ (at $V_{GS}=4.5V$ )	< 3.4mΩ
$R_{SS(ON)}$ (at $V_{GS}=3.8V$ )	< 3.8mΩ
$R_{SS(ON)}$ (at $V_{GS}=3.1V$ )	< 4.4mΩ
$R_{SS(ON)}$ (at $V_{GS}=2.5V$ )	< 5.3mΩ

### Typical ESD protection

HBM Class 2



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AOCA32106E	AlphaDFN™ 1.84x1.96_10	Tape & Reel	8000

### Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Rating	Units
Source-Source Voltage	$V_{SS}$	12	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$	V
Source Current(DC) <sup>Note1</sup>	$I_S$   $T_A=25^\circ\text{C}$	25	A
Source Current(Pulse) <sup>Note2</sup>	$I_{SM}$	130	
Power Dissipation <sup>Note1</sup>	$P_D$   $T_A=25^\circ\text{C}$	2.8	W
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	°C

### Thermal Characteristics

Parameter	Symbol	Typical	Units
Maximum Junction-to-Ambient   $t \leq 10\text{s}$	$R_{\theta JA}$	35	°C/W
Maximum Junction-to-Ambient   Steady-State		45	°C/W

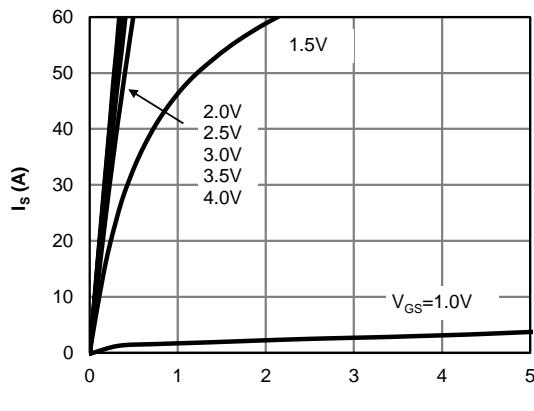
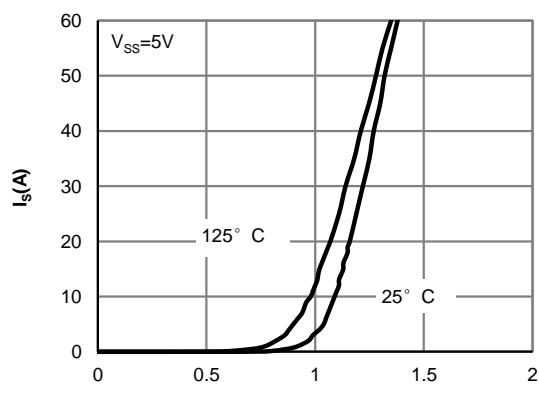
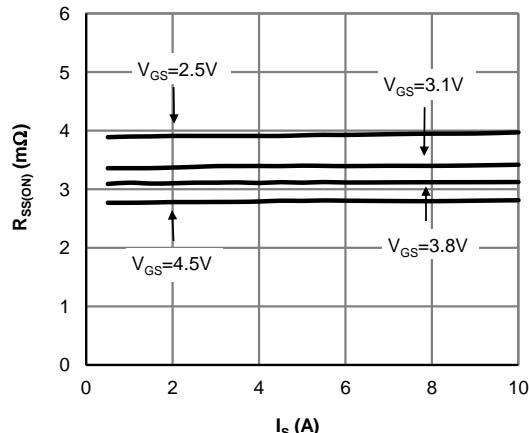
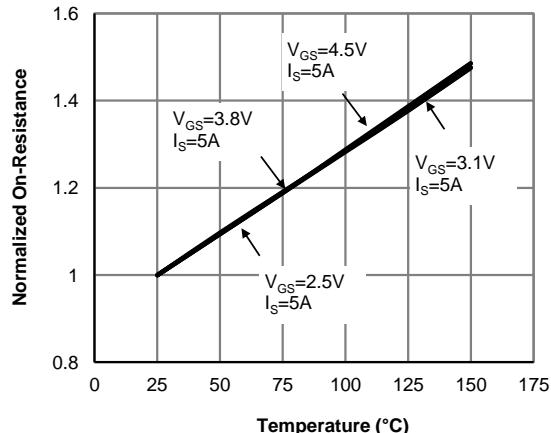
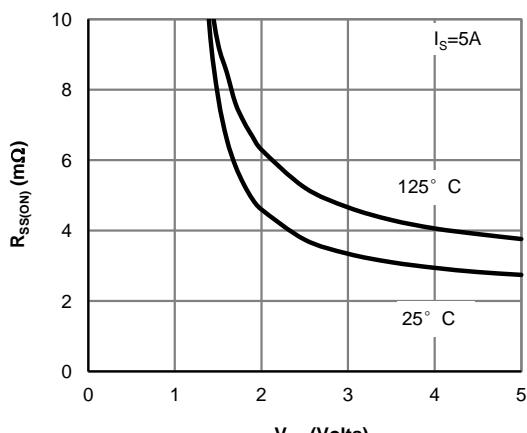
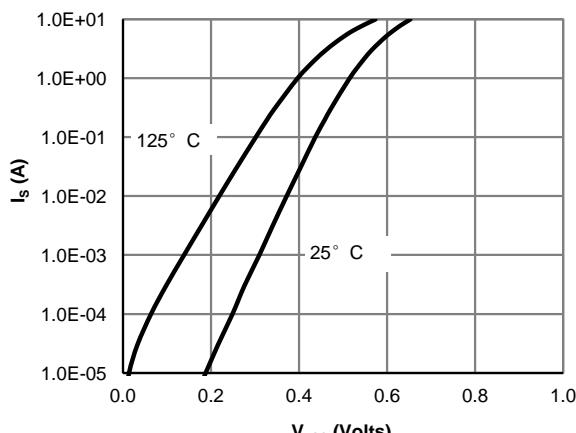
**Note 1.**  $I_S$  rated value is based on bare silicon. Mounted on 70mmx70mm FR-4 board.

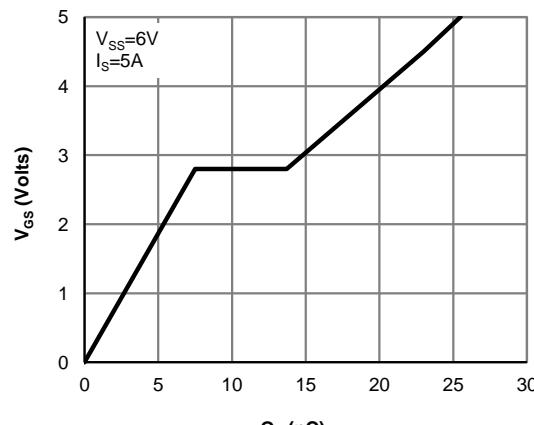
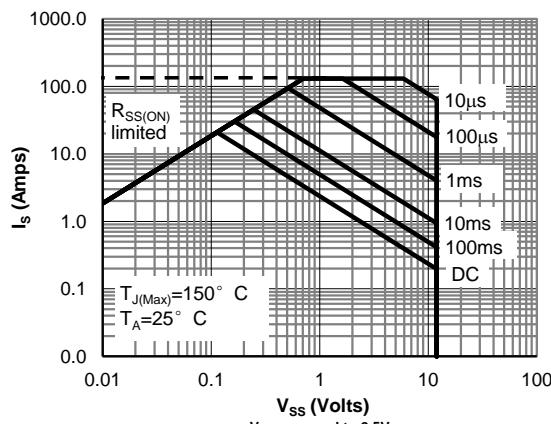
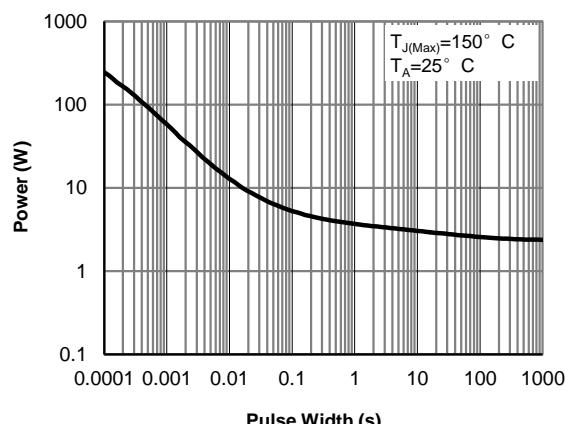
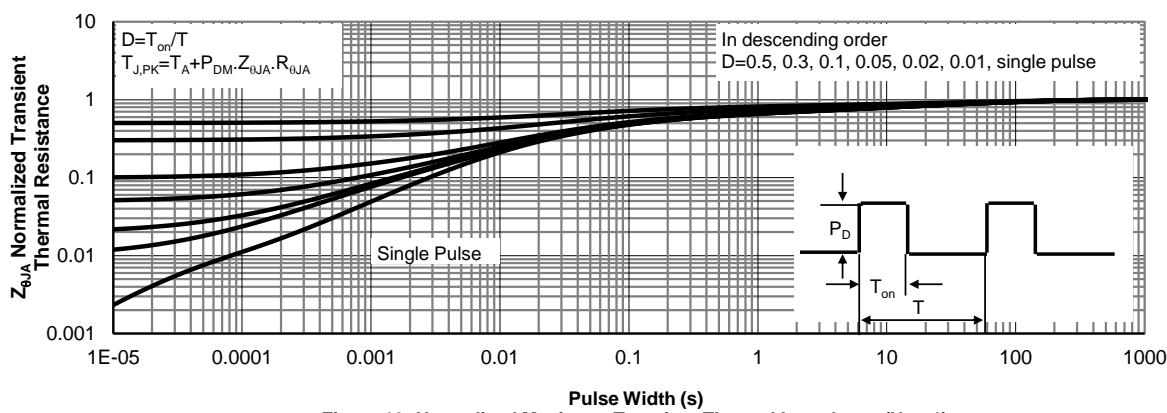
**Note 2.** PW <10  $\mu\text{s}$  pulses, duty cycle 1% max.

**Electrical Characteristics ( $T_J=25^\circ\text{C}$  unless otherwise noted)**

Symbol	Parameter	Conditions	Min	Typ	Max	Units
<b>STATIC PARAMETERS</b>						
$\text{BV}_{\text{SSS}}$	Source-Source Breakdown Voltage	$I_S=250\mu\text{A}, V_{GS}=0\text{V}$	Test Circuit 6	12		V
$I_{\text{SSS}}$	Zero Gate Voltage Source Current	$V_{SS}=12\text{V}, V_{GS}=0\text{V}$	Test Circuit 1 $T_J=55^\circ\text{C}$		1 5	$\mu\text{A}$
$I_{GSS}$	Gate leakage current	$V_{SS}=0\text{V}, V_{GS}=\pm 8\text{V}$	Test Circuit 2		$\pm 10$	$\mu\text{A}$
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{SS}=V_{GS}, I_S=250\mu\text{A}$	Test Circuit 3	0.4	0.7	1.1
$R_{SS(\text{ON})}$	Static Source to Source On-Resistance	$V_{GS}=4.5\text{V}, I_S=5\text{A}$	Test Circuit 4	1.9	2.8	3.4
		$T_J=125^\circ\text{C}$		2.7	3.85	4.7
		$V_{GS}=3.8\text{V}, I_S=5\text{A}$	Test Circuit 4	2.1	3.1	3.8
		$V_{GS}=3.1\text{V}, I_S=5\text{A}$	Test Circuit 4	2.3	3.4	4.4
		$V_{GS}=2.5\text{V}, I_S=5\text{A}$	Test Circuit 4	2.7	3.9	5.3
		$V_{GS}=1.8\text{V}, I_S=5\text{A}$	Test Circuit 4	2.1	3.1	3.8
		$V_{GS}=1.2\text{V}, I_S=5\text{A}$	Test Circuit 4	2.3	3.4	4.4
		$V_{GS}=0.8\text{V}, I_S=5\text{A}$	Test Circuit 4	2.7	3.9	5.3
$g_{FS}$	Forward Transconductance	$V_{SS}=5\text{V}, I_S=5\text{A}$	Test Circuit 3		50	S
$V_{FSS}$	Forward Source to Source Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$	Test Circuit 5		0.55	1
<b>DYNAMIC PARAMETERS</b>						
$R_g$	Gate resistance	$f=1\text{MHz}$			1.5	$\text{k}\Omega$
<b>SWITCHING PARAMETERS</b>						
$Q_g$	Total Gate Charge	$V_{G1S1}=4.5\text{V}, V_{SS}=6\text{V}, I_S=5\text{A}$			23	nC
$t_{D(on)}$	Turn-On DelayTime				1.1	$\mu\text{s}$
$t_r$	Turn-On Rise Time	$V_{G1S1}=4.5\text{V}, V_{SS}=6\text{V}, R_L=1.2\Omega,$ $R_{\text{GEN}}=3\Omega$	Test Circuit 8		3.2	$\mu\text{s}$
$t_{D(off)}$	Turn-Off DelayTime				5.3	$\mu\text{s}$
$t_f$	Turn-Off Fall Time				11	$\mu\text{s}$

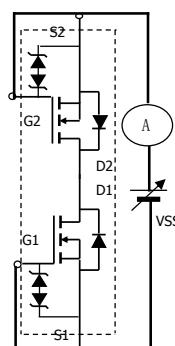
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**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

**Figure 1: On-Region Characteristics**

**Figure 2: Transfer Characteristics**

**Figure 3: On-Resistance vs. Source Current and Gate Voltage**

**Figure 4: On-Resistance vs. Junction Temperature**

**Figure 5: On-Resistance vs. Gate-Source Voltage**

**Figure 6: Forward Source to Source Characteristics**

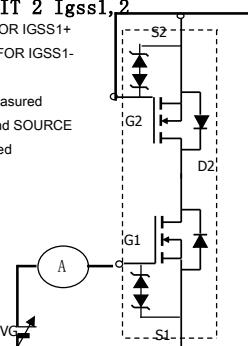
**TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS**

**Figure 7: Gate-Charge Characteristics**

**Figure 8: Maximum Forward Biased Safe Operating Area (Note1)**

**Figure 9: Single Pulse Power Rating Junction-to-Ambient (Note1)**

**Figure 10: Normalized Maximum Transient Thermal Impedance (Note1)**



**TEST CIRCUIT 1 Isss**  
POSITIVE VSS FOR ISSS+  
NEGATIVE VSS FOR ISSS-

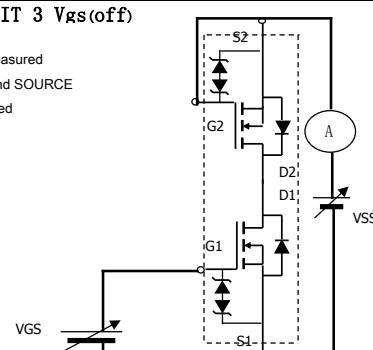


**TEST CIRCUIT 2 Igss1,2**  
POSITIVE VGS FOR IGSS1+  
NEGATIVE VGS FOR IGSS1-



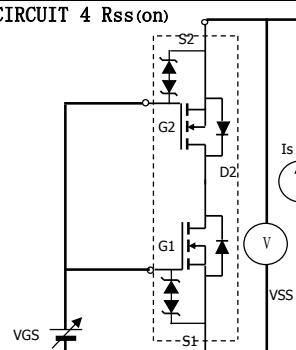
**TEST CIRCUIT 3 Vgs(off)**

When FET1 is measured  
between GATE and SOURCE  
of FET2 are shorted



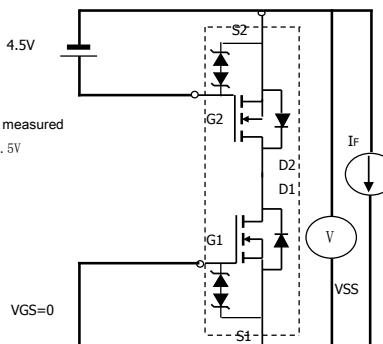
**TEST CIRCUIT 4 Rss(on)**

Vss/Is



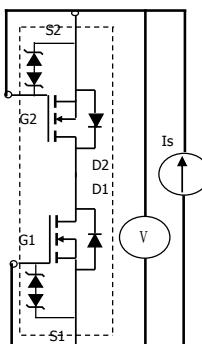
**TEST CIRCUIT 5 VF(ss)1,2**

When FET1 measured  
FET2 VGS=4.5V



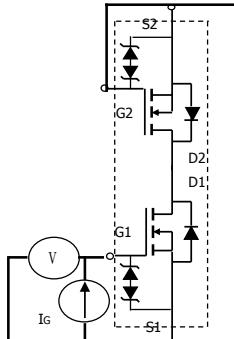
**TEST CIRCUIT 6 BVdss**

POSITIVE VSS FOR ISSS+  
NEGATIVE VSS FOR ISSS-



**TEST CIRCUIT 7 BVgs01,2**  
POSITIVE VSS FOR ISSS+  
NEGATIVE VSS FOR ISSS-

When FET1 is measured  
between GATE and SOURCE  
of FET2 are shorted



**TEST CIRCUIT 8**  
Switching time

